

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1-11. (Canceled).

12. (Currently Amended) A process for producing a laser engravable printing substrate, comprising the steps of: forming a photosensitive resin composition layer on a cylindrical support or a sheeted support; and applying light to the formed photosensitive resin composition layer to form a cured photosensitive resin layer, and then adjusting a thickness of the cured photosensitive resin layer and shaping a surface of the cured photosensitive resin layer, wherein the light applied to the photosensitive resin composition layer includes light having a wavelength of 200 nm or more and 450 nm or less, and an illuminance of light at a surface of the photosensitive resin composition layer is 20 mW/cm² or more when measured using a UV meter configured with a filter which transmits light with a relative spectral sensitivity peak at 350 nm, ~~(trade mark "UV-M02" manufactured by ORC Manufacturing Co., Ltd.)~~ and a filter ~~(trade mark "UV-35-APR Filter" manufactured by ORC Manufacturing Co., Ltd.)~~, and 3 mW/cm² or more when measured using the UV meter configured with ~~and a filter which~~ transmits light with a relative spectral sensitivity peak at 250 nm ~~(trade mark "UV-25-Filter" manufactured by ORC Manufacturing Co., Ltd.)~~.

13. (Currently Amended) The process according to claim 12, wherein the illuminance of light at a surface of the photosensitive resin composition layer is 20 mW/cm² or more and 2 W/cm² or less when measured using a UV meter configured with a filter which transmits light with a relative spectral sensitivity peak at 350 nm,

~~(trade mark "UV-M02" manufactured by ORC Manufacturing Co., Ltd.) and a filter (trade mark "UV-35-APR Filter" manufactured by ORC Manufacturing Co., Ltd.), and 3 mW/cm² or more and 2 W/cm² or less when measured using the UV meter configured with and a filter which transmits light with a relative spectral sensitivity peak at 250 nm(trade mark "UV-25 Filter" manufactured by ORC Manufacturing Co., Ltd.).~~

14. (Previously Presented) The process according to claim 13, wherein said cured photosensitive resin layer has a thickness of 50 μ m or more and 50 mm or less.

15. (Currently Amended) The process according to any one of claims 12 to 14, further comprising a step of applying light to the cured photosensitive resin layer again after the step of adjusting the thickness of the cured photosensitive resin layer and shaping the surface of the cured photosensitive resin layer, wherein the light applied to the cured photosensitive resin layer again includes light having a wavelength of 200 nm or more and 450 nm or less, and the illuminance of light at the surface of the cured photosensitive resin layer is 20 mW/cm² or more and 2 W/cm² or less when measured using a UV meter configured with a filter which transmits light with a relative spectral sensitivity peak at 350 nm, ~~(trade mark "UV-M02" manufactured by ORC Manufacturing Co., Ltd.) and a filter (trade mark "UV-35-APR Filter" manufactured by ORC Manufacturing Co., Ltd.), and 3 mW/cm² or more and 2 W/cm² or less when measured using the UV meter configured with and a filter which transmits light with a relative spectral sensitivity peak at 250 nm(trade mark "UV-25 Filter" manufactured by ORC Manufacturing Co., Ltd.).~~

16. (Previously Presented) The process according to any one of claims 12 to 14, wherein the light is applied to the photosensitive resin composition layer or the cured photosensitive resin layer in the air.

17. (Previously Presented) The process according to any one of claims 12 to 14, wherein the temperature of the photosensitive resin composition layer or the cured photosensitive resin layer is -50°C or more and 150°C or less.

18. (Previously Presented) The process according to any one of claims 12 to 14, wherein the photosensitive resin composition layer is liquid at 20°C .

19. (Previously Presented) The process according to any one of claims 12 to 14, wherein the photosensitive resin composition layer is solid at 20°C .

20. (Previously Presented) The process according to any one of claims 12 to 14, wherein the cured photosensitive resin layer is a seamless layer.

21. (Currently Amended) The process according to any one of claims 12 to 14, wherein ~~an optical system~~ a lens or a concave mirror for collecting light exists between a light source for applying light and the photosensitive resin composition layer.

22. (Previously Presented) The process according to any one of claims 12 to 14, wherein the printing substrate is a flexographic printing original plate on which a concavo-convex pattern can be formed by applying laser light, a letter press printing original plate, a gravure printing original plate, a screen printing original plate on which a perforated pattern can be formed by applying laser light, or a blanket for offset printing.

23. (Previously Presented) A laser engravable printing substrate, characterized in that in measurement of dynamic viscoelasticity of a photo-cured photosensitive resin using a non-resonant forced stretch vibration apparatus, a loss tangent ($\tan \delta$) defined

by a ratio of a loss elastic modulus (E'') to a storage elastic modulus (E') has a peak in a measurement temperature range of -100°C or more and 20°C or less, and when $\tan \delta$ has a peak in a temperature range of -50°C or more and 20°C or less, the value of $\tan \delta$ at the peak temperature is 0.87 or more and 1.5 or less, and when $\tan \delta$ has a peak in a temperature range of -100°C or more and less than -50°C , the value of $\tan \delta$ at the peak temperature is 0.7 or more and 1.5 or less.